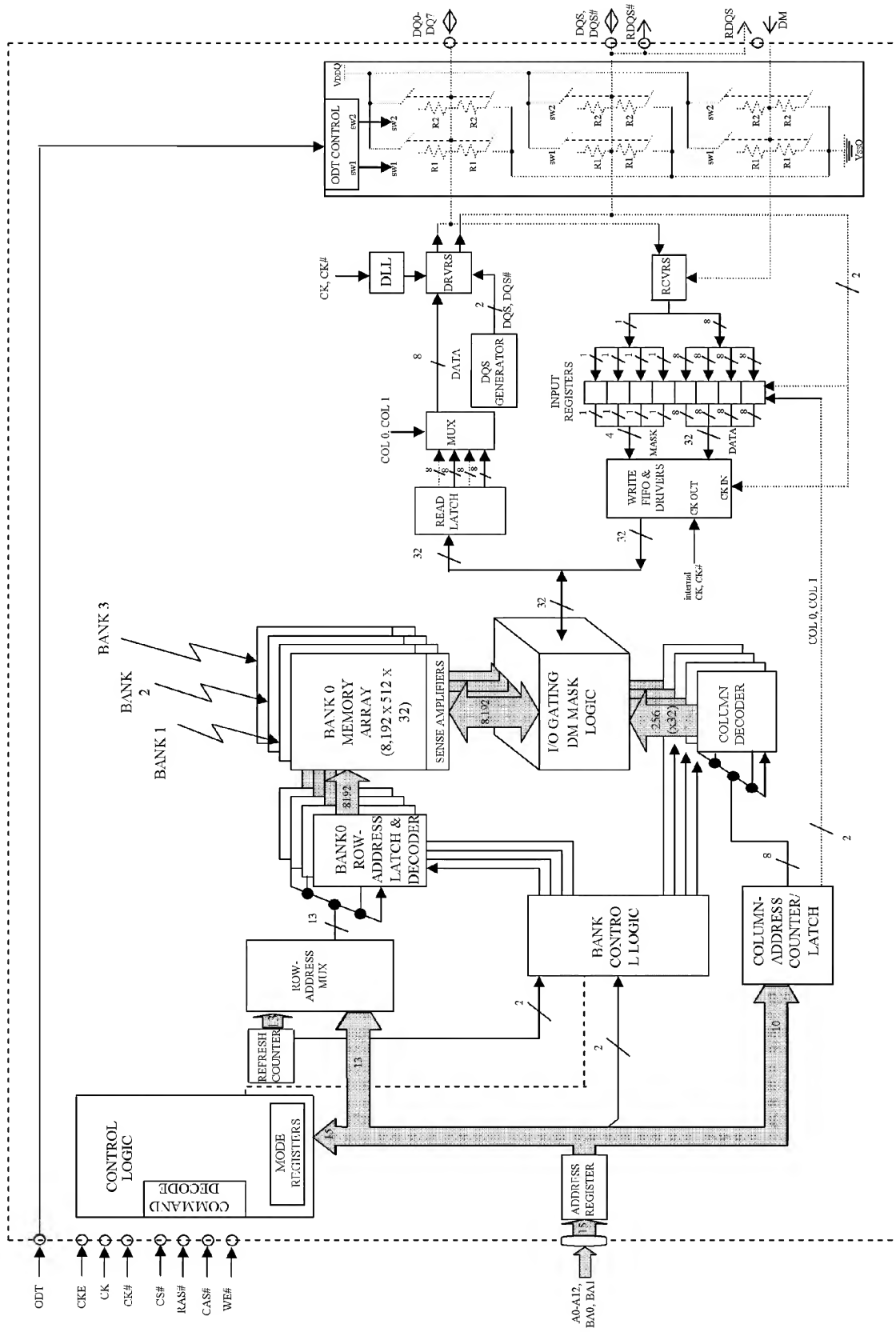


[illegible]

FIGURE 2 (Prior Art)



[illegible]

FIGURE 4
(Prior Art)

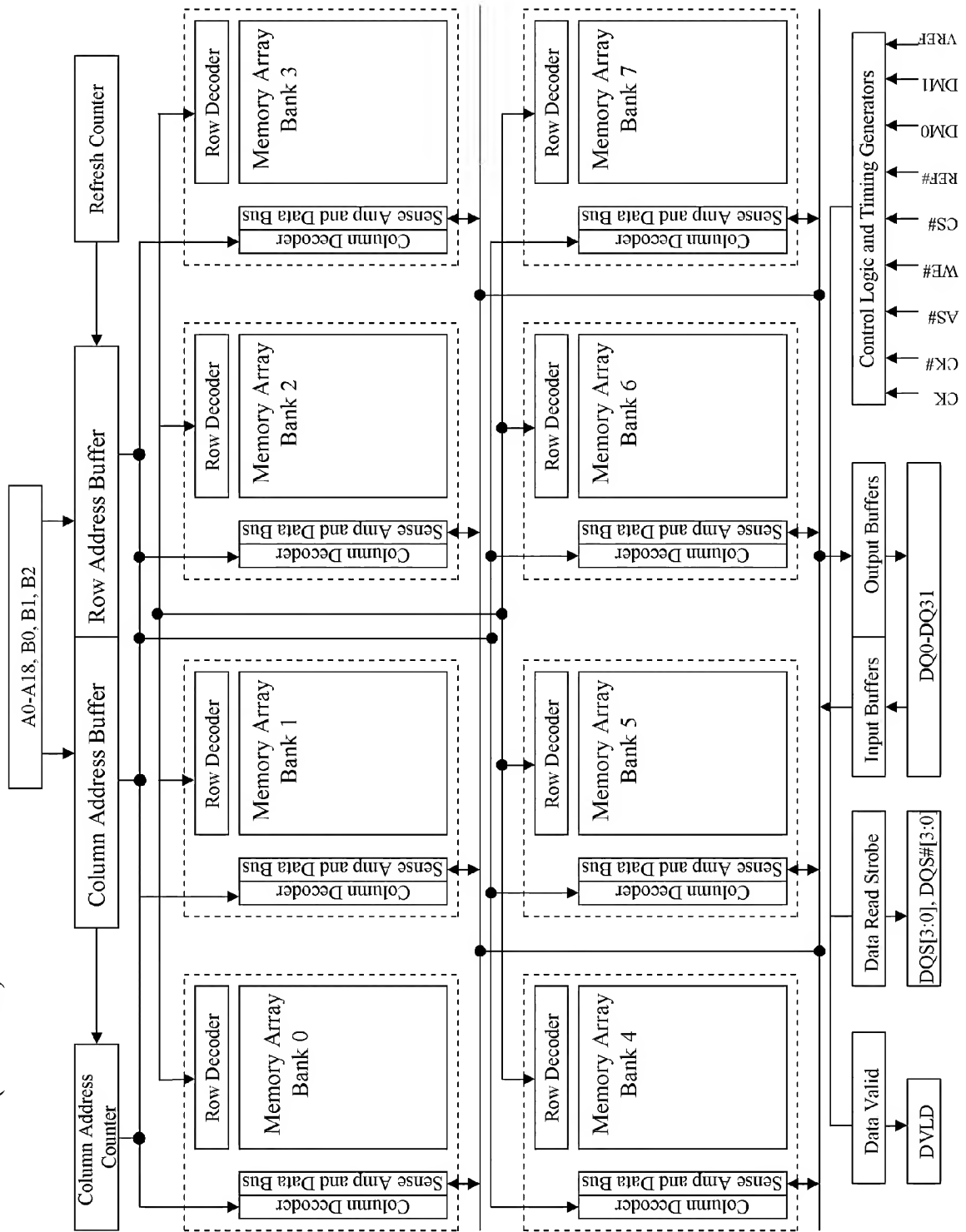


FIGURE 5
(Prior Art)

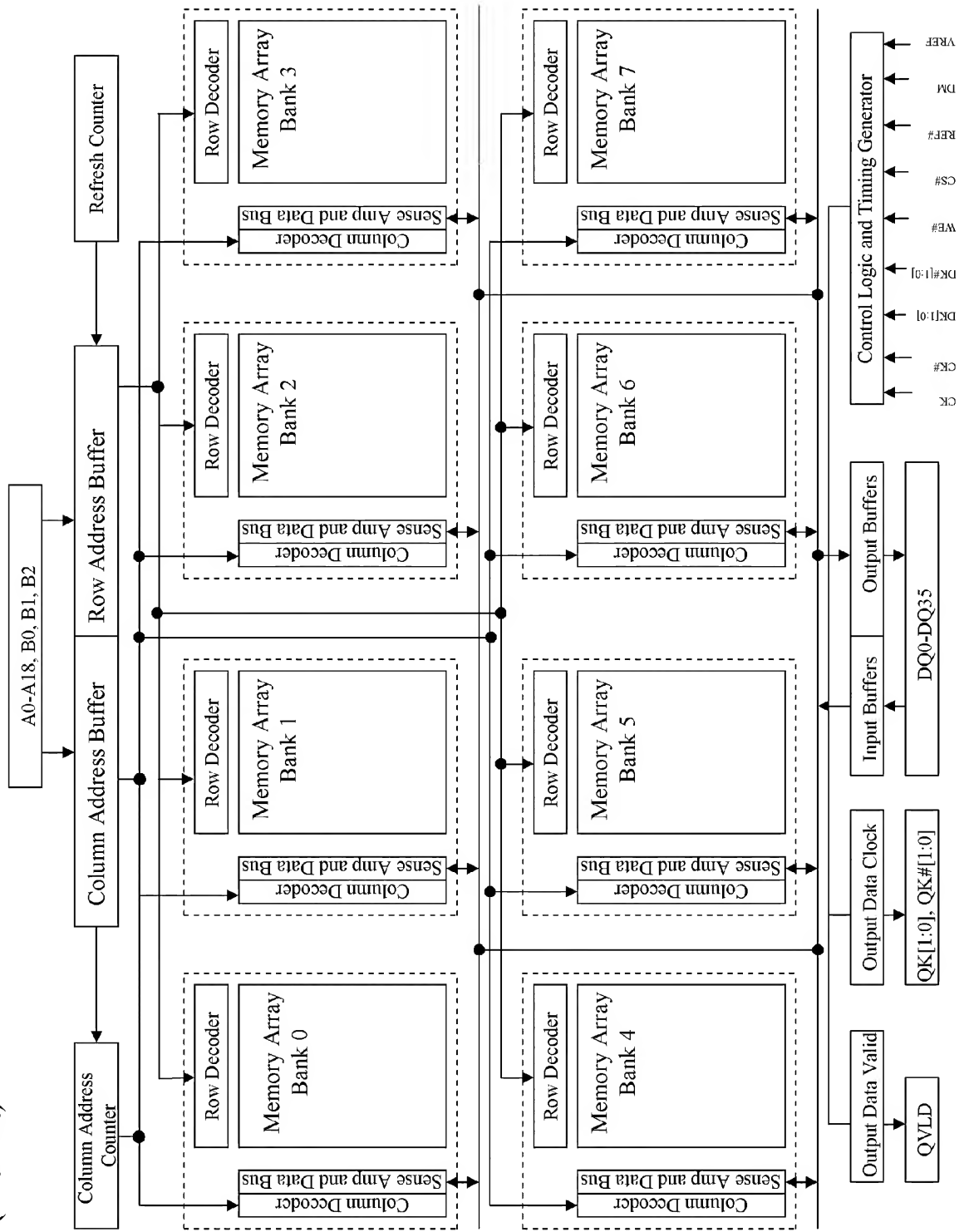
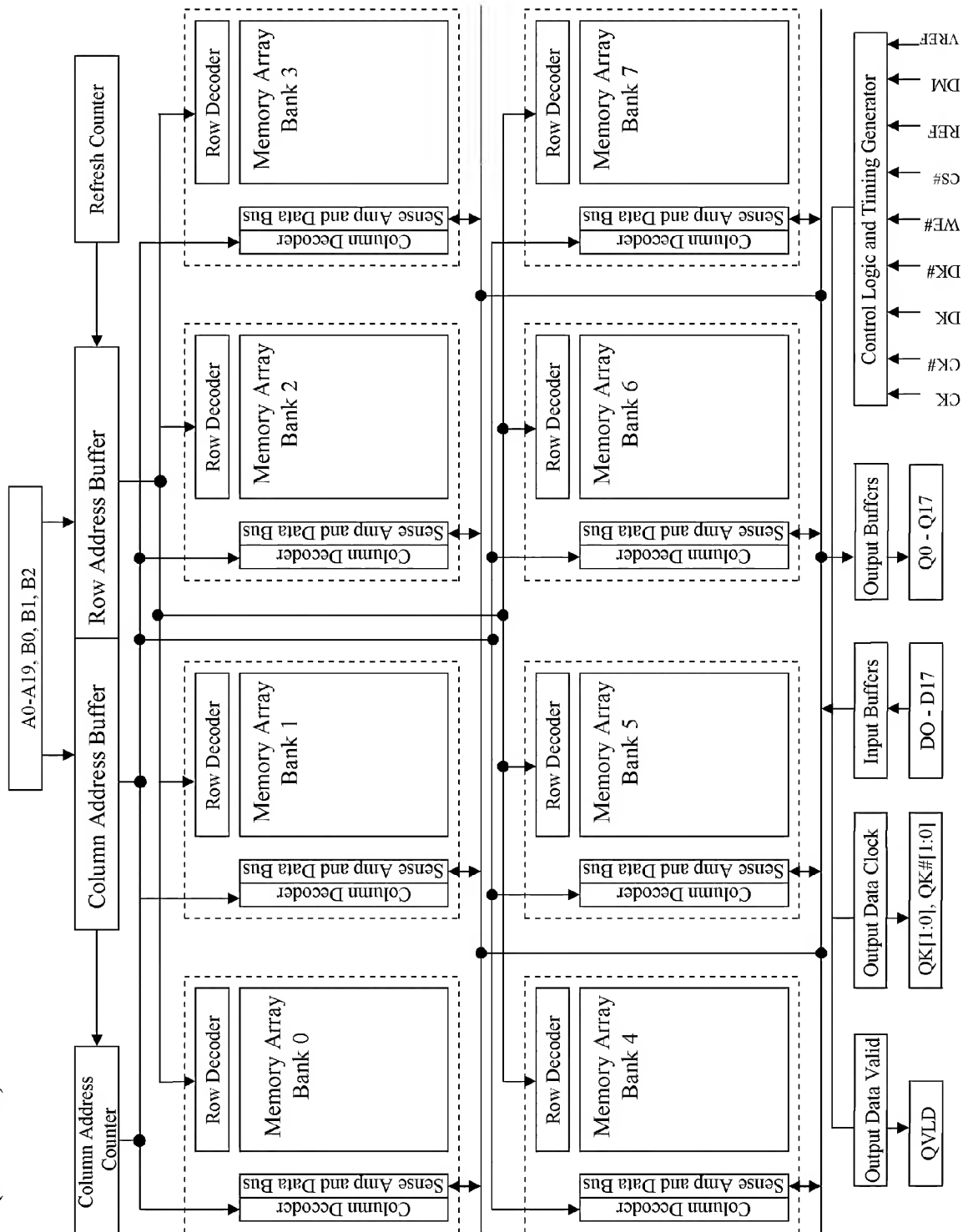


FIGURE 6
(Prior Art)

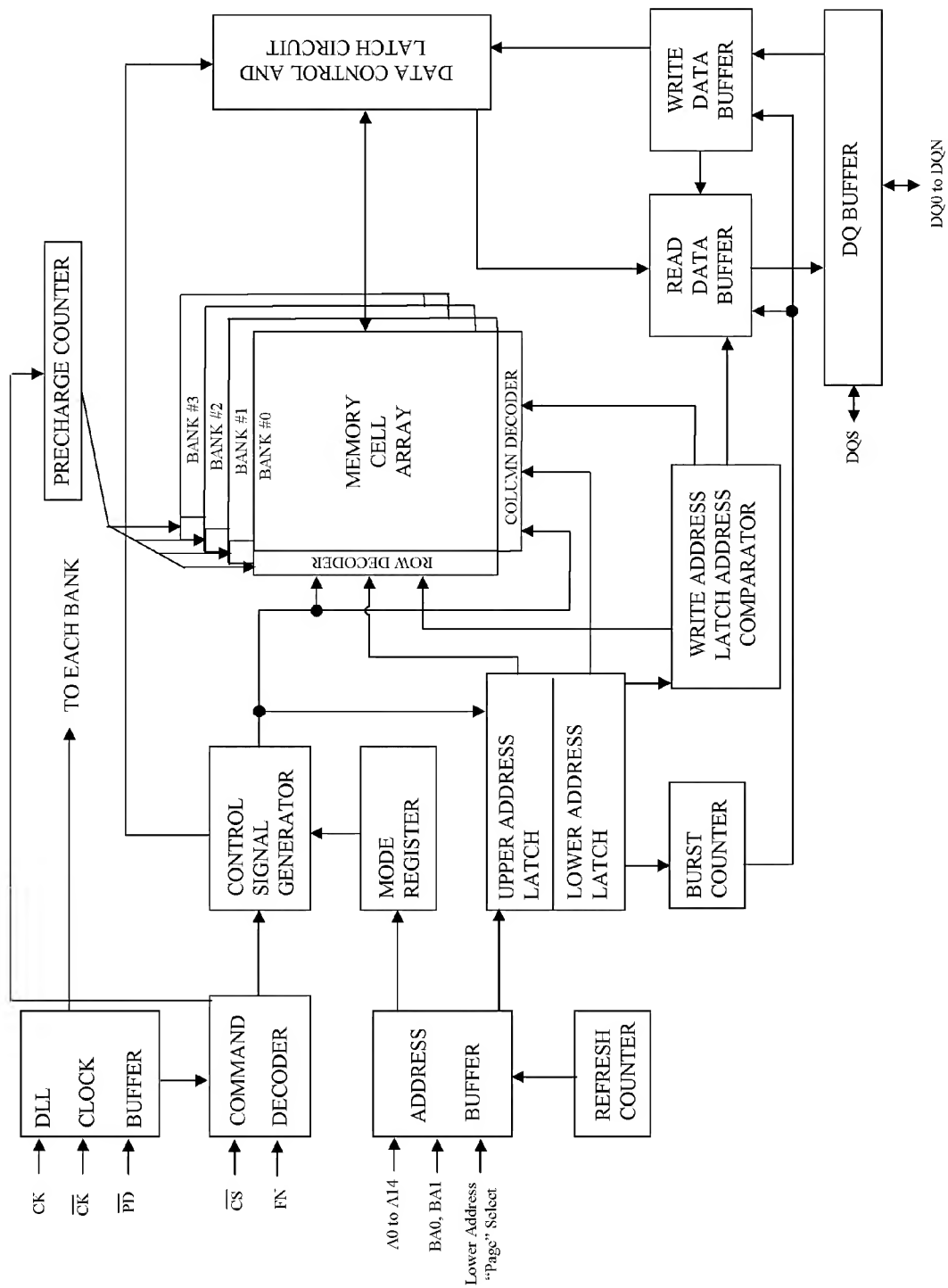


The diagram illustrates a memory architecture with the following components and data paths:

- Inputs:** ODT, CKE, CK, CK#, CS#, RAS#, CAS#, WE#, A0-A12, BAO, BA1.
- Control Logic:** Includes a COMMAND DECODE block and MODE REGISTERS, which interface with an ADDRESS REGISTER (15 bits).
- Memory Banks:** BANK 0, BANK 1, BANK 2, and BANK 3. BANK 0 is detailed as a MEMORY ARRAY (8,192 x 512 x 32).
- Address Decoding:** A BANK0 ROW-ADDRESS LATCH & DECODER (13 bits) and a COLUMN-ADDRESS COUNTER/LATCH (10 bits) are used to address the memory array.
- Data Flow:**
 - DATA (32 bits) flows from the memory array through SENSE AMPLIFIERS and LOGIC to the I/O MASK LOGIC.
 - DATA (32 bits) flows from the I/O MASK LOGIC through a COLUMN DECODER to the COLUMN-ADDRESS COUNTER/LATCH.
 - DATA (32 bits) flows from the COLUMN-ADDRESS COUNTER/LATCH to the COLUMN-ADDRESS COUNTER/LATCH.
 - DATA (32 bits) flows from the COLUMN-ADDRESS COUNTER/LATCH to the COLUMN-ADDRESS COUNTER/LATCH.
- Output Registers:** INPUT REGISTERS (16 registers, 1 bit each) and WRITE FIFO & DRIVERS (32 bits) are used for data output.
- Timing and Control:** A PRECHARGE COUNTER, REFRESH COUNTER, and BANK CONTROL LOGIC are used to manage memory operations.
- Physical Layer:** The diagram shows the physical layer connections for DQ0-DQ7, DQS, DQS#, RDQS, RDQS#, and DM, along with VDDQ and VSSQ power pins.

[illegible]

FIGURE 10



Burst Read with Auto Precharge (JEDEC Standard DDR2 DRAM Specification, September 2003)

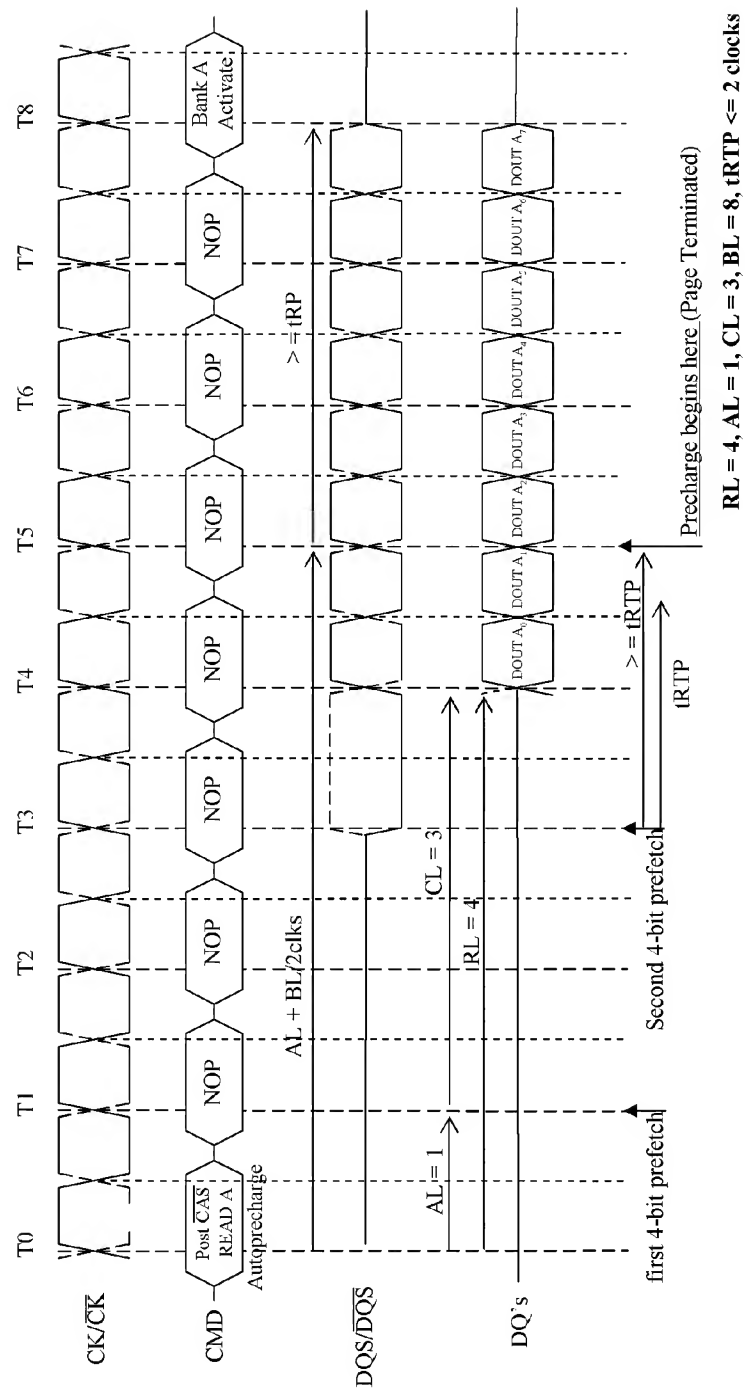
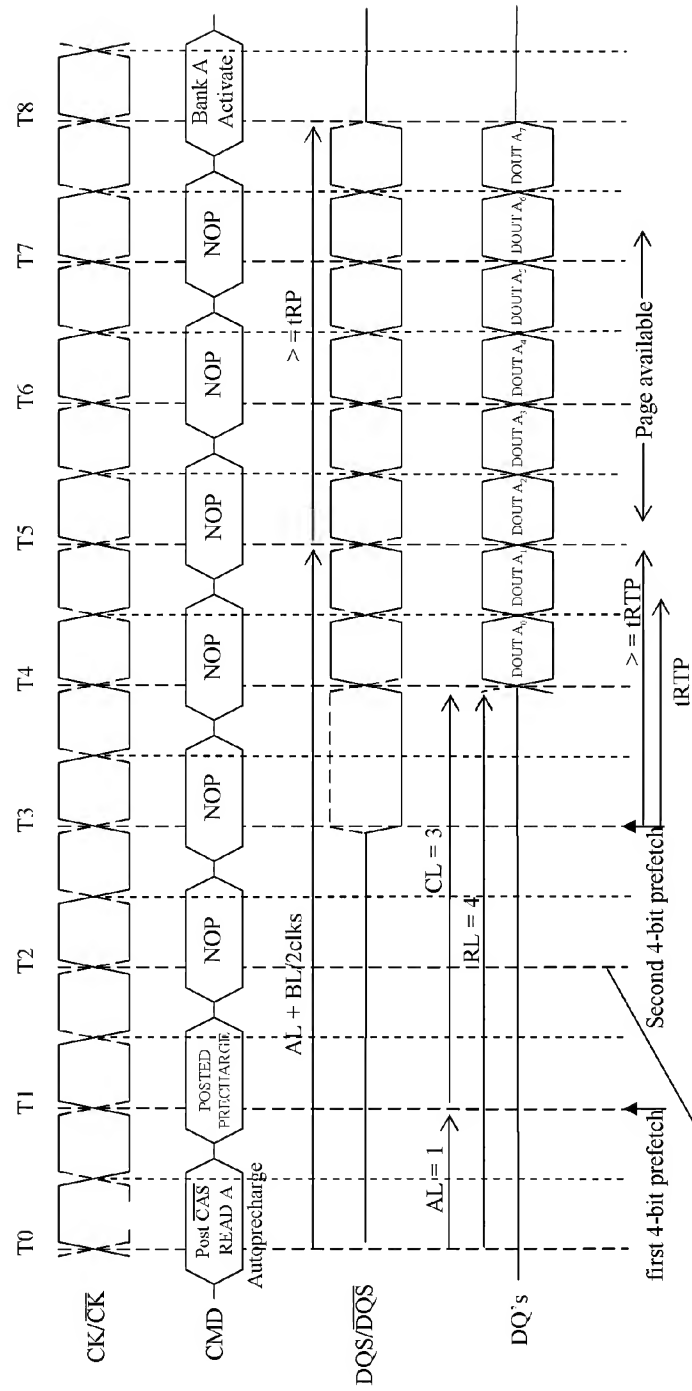


FIGURE 11

Burst Read with Posted Precharge



RL = 4, AL = 1, CL = 3, BL = 8, IRTP ≤ 2 clocks

Internal Precharge (Programmable) enable activated

FIGURE 12

